PC715V0NSZX/ PC715V0YSZX

■ Features

- 1. High sensitivity (CTR:MIN. 600%)
- 2. Isolation voltage (Viso (rms):5kV)
- Recognized by UL, file No.E64380
 Approved by TÜV (VDE0884)(PC715V0YSZX)
- 4. 6-pin DIP package

■ Applications

- 1. Home appliances
- 2. Programmable controllers
- 3. Peripheral equipment of personal computers

■ Model Line-up

Model No.	* Safty Standard Approval		
	UL	TÜV(VDE0884)	
PC715V0NSZX	0	_	
PC715V0YSZX	0	0	

^{*} Application Model No. PC715V

■ Absolute Maximum Ratings

(Ta	=2.5	°C

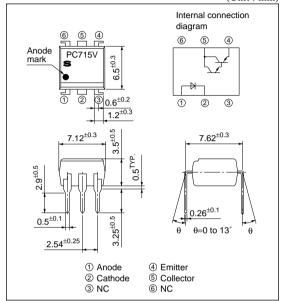
Parameter		Symbol	Rating	Unit
Input	Forward current	IF	50	mA
	*1 Peak forward current	IFM	1	A
	Reverse voltage	V_R	6	V
	Power dissipation	P	70	mW
Output	Collector-emitter voltage	Vceo	35	V
	Emitter-collector voltage	VECO	6	V
	Collector current	Ic	80	mA
	Collector power dissipation	Pc	150	mW
Total power dissipation		Ptot	170	mW
*2 Isolation voltage		Viso (rms)	5	kV
Operating temperature		Topr	-25 to +100	°C
Storage temperature		Tstg	-40 to +125	°C
*3 Soldering temperature		Tsol	260	°C

^{*1} Pulse width≤100µs, Duty ratio=0.001

High Sensitivity Type Photocoupler

■ Outline Dimensions

(Unit: mm)



^{*2 40} to 60% RH, AC for 1 min

^{*3} For 10 s

■ Electro	o-optical Charac	teristics					(Ta=25°C)
	Parameter			Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage		VF	I _F =10mA	_	1.2	1.4	V
	Peak forward voltage		V _{FM}	I _{FM} =0.5A	_	-	3.0	V
	Reverse current		IR	V _R =4V	_	_	10	μΑ
	Terminal capacitance		Ct	V=0, f=1kHz	_	30	250	pF
Output	Collector dark current		Iceo	Vce=10V, I _F =0	_	_	10-6	A
Transfer charac- teristics	Collector current		Ic	I _F =1mA, V _{CE} =2V	6	160	75	mA
	Collector-emitter saturation voltage		V _{CE(sat)}	I _F =20mA, I _C =5mA	-	_	1.0	V
	Isolation resistance		Riso	DC500V, 40 to 60%RH	5×10 ¹⁰	1011	_	Ω
	Floating capacitance		Cf	V=0, f=1MHz	_	0.6	1.0	pF
	Cut-off frequency		fc	Vce=2V, Ic=2mA, Rl=100Ω, -3dB	_	6	_	kHz
	Response time	Rise time	tr	Vce=2V, Ic=10mA	-	60	250	μs
		Fall time	tf	RL=100Ω	_	53	250	μs

Fig.1 Forward Current vs. Ambient Temperature

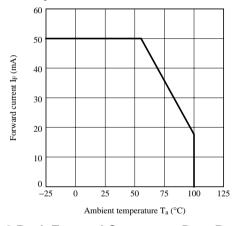


Fig.2 Collector Power Dissipation vs. Ambient Temperature

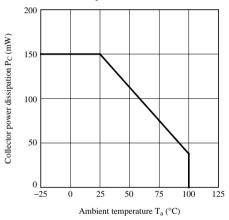


Fig.3 Peak Forward Current vs. Duty Ratio

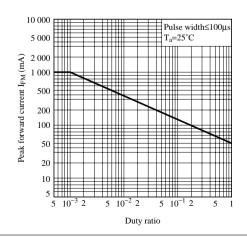


Fig.4 Forward Current vs. Forward Voltage

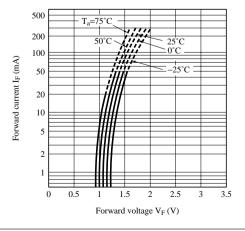


Fig.5 Current Transfer Ratio vs. Forward Current

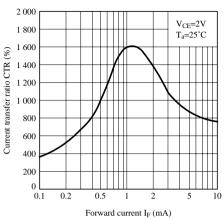


Fig.7 Collector Current vs. Collector-emitter Voltage

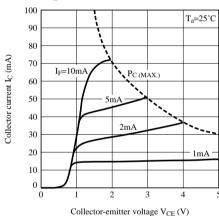


Fig.9 Collector - emitter Saturation Voltage vs. Ambient Temperature

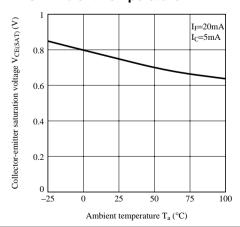


Fig.6 Collector Current vs. Collector-emitter Voltage

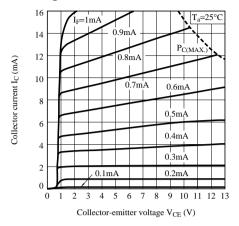


Fig.8 Relative Current Transfer Ratio vs.
Ambient Temperature

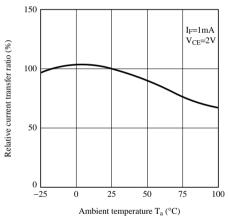


Fig.10 Collector Dark Current vs. Ambient Temperature

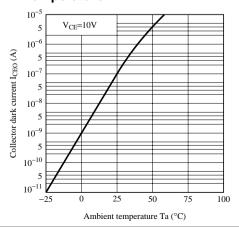


Fig.11 Response Time vs. Load Resistance

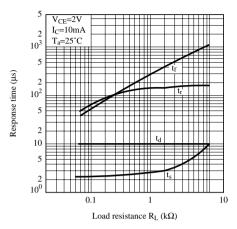


Fig.13 Frequency Response

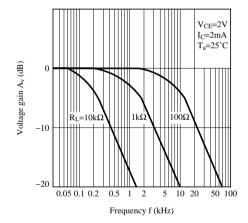


Fig.12 Test Circuit for Response Time

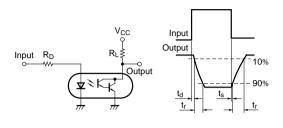
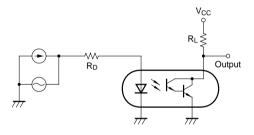


Fig.14 Test Circuit for Frequency Response



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